

SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

Specification

MATERIAL:

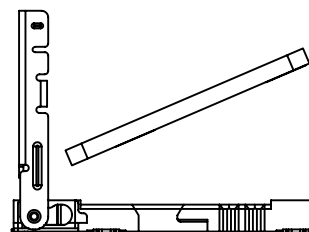
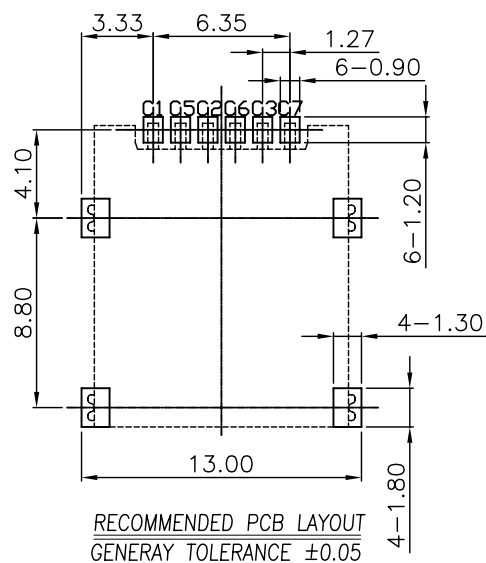
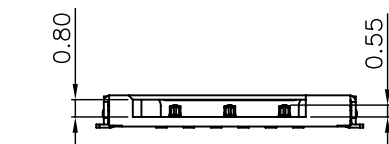
Insulator: High Temperature Thermoplastic, 94V-0.
 Contact: Copper Alloy
 SHELL: SUS

PLATING:

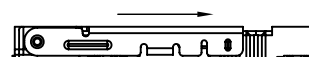
Contact: Plated 50u" Ni Overall Contact ALL Au 1U,
 Shell: ALL NI 30U/MIN

Electrical:

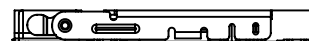
Current Rating : 0.5mA AC/DC max.
 Voltage Rating : 125V AC/DC
 Ambient Temperature Range : -20°C~+60°C
 Storage Temperature Range : -40°C~+70°C
 Ambient Humidity Range : 95% R.H. Max.
 Contact Resistance: 80mΩ max.
 Insulation Resistance: 100MΩ min./100V DC
 Mating Cycles: 5,000 Insertions
 Reflow peak temp.: 260°C ±5°C, 3~5 S



STEP 1 INSERT Micro-SIM CARD



STEP 2 PUSH THE SHELL



STEP 3 FINISH



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TOLERANCE:
 X.X ±0.30
 X.XX ±0.25
 X.XXX ±0.15

X: ±2° X.X° ±0.5°

UNIT: mm [inch]

SCALE: 1:1 SIZE: A4

DRAWN BY :
 陈一鸣

DATE :
 2014-02-23

PART NAME:
 NANO SIM 6P 掀盖1.5H

CHECKED BY:
 马跃

DATE :
 2014-02-23

PART NO. HYC240-SIM06-150

APPROVED BY:
 邱国夷

DATE :
 2014-02-23

DRAW NO: HYC-SIM191128102

SHEET NO. 1 OF 1